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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Honeycutt et al, Jeffrey W.

Application No.: 09/965,142

Filed: 08/30/2000

Examiner: Unknown

For: Transistor Structures, Methods of Forming Transistor Structures, and Methods of Forming

Insulative Material Against Conductive Structures

Assistant Commissioner for Patents Office of Initial Patent Examination Customer Service Center Washington, D.C. 20231

REQUEST FOR CORRECTED FILING RECEIPT

- 1. Attached is a copy of the official filing receipt received from the PTO in the above application for which issuance of a corrected filing receipt is respectfully requested.
- 2. There is an error with respect to the following, which is incorrectly entered.

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8a)

I hereby certify that this correspondence is, on the date shown below, being:

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deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

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(Request for Corrected Filing Receipt—page 1 of 2)



Error in

Correct data

1. Transistor Structures, Methods of Forming Transistor Structures, and Methods of Forming Insulative Material Against Conductive Structures

3. The correction is not due to any error by applicant and no fee is due.

SIGNATURE OF PRACTITIONER

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/651 422	08/30/2000	2811	1122	M122-1332	9	31	6

021567
WELLS ST JOHN ROBERTS GREGORY AND MATKIN SUITE 1300
601 W FIRST AVENUE
SPOKANE, WA 992013828

FILING RECEIPT

OC000000005489669

Date Mailed: 10/20/2000

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Jeffrey W. Honeycutt, Boise, ID; Hassan Shahjamali, Boise, ID; Daniel Smith, Boise, ID;

Continuing Data as Claimed by Applicant

Foreign Applications

If Required, Foreign Filing License Granted 10/19/2000

Title

Structures

Transistor structres, methods of forming transistor structures, and methods of forming insulative material against conductive Structures

Preliminary Class

257

Data entry by: MIDDLETON, MATTIE Team: OIPE Date: 10/20/2000

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APPLICATION FOR LETTERS PATENT

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Transistor Structures, Methods of Forming Transistor Structures, and Methods of Forming Insulative Material Against Conductive Structures

INVENTORS

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ATTORNEY'S DOCKET NO. MI22-1332